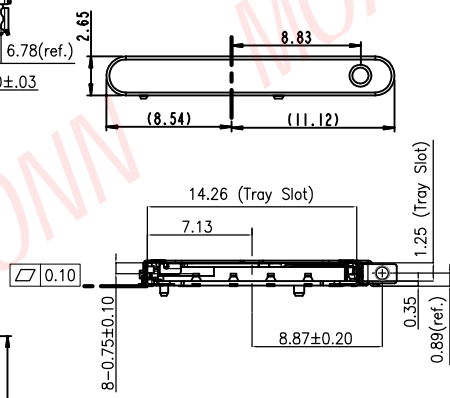
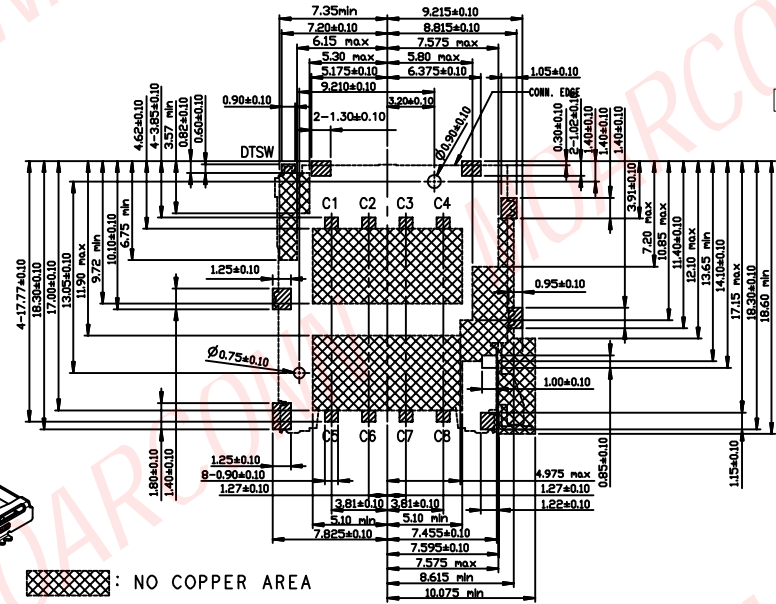
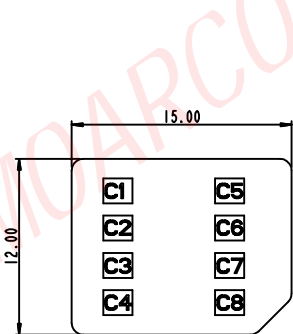
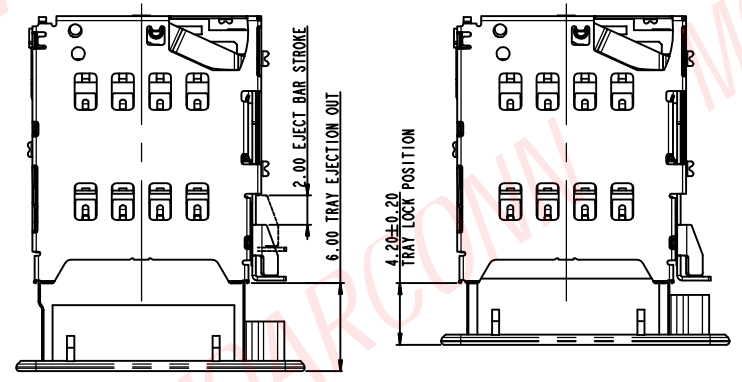
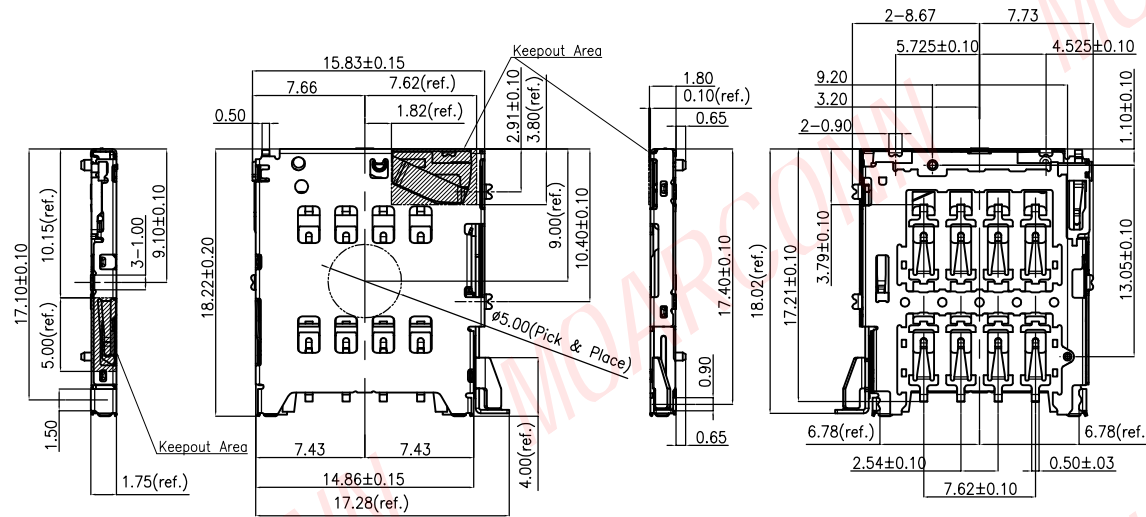
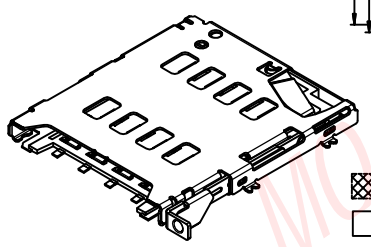


All materials, plating and process meet HF requirements.

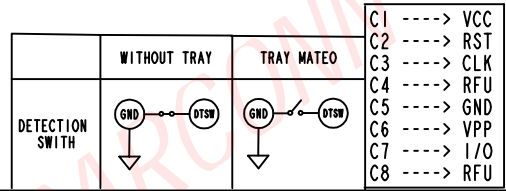


- Notes:
- Material:
 - Plastic Housing: LCP, UL94V-0, Black
 - Contact Terminal: Phosphor Bronze
 - Cover: SUS301, Thickness=0.15mm
 - Plating:
 - Contact Terminal:
 - Contact Area: Au 1U" Min.
 - Solder area: Au 1U" Min.
 - Underplating: Ni overall 50U" Min.
 - Cover:
 - Underplating: Ni overall 50U"
 - Solder area: Au 1U" Min.
 - Mechanical:
 - Life cycles: 5000.
 - Electrical:
 - Voltage Rating: 30V AC RMS
 - Current Rating: 0.5A AC RMS Max
 - Operating Temperature: -20°C to +85°C
 - Dielectric Withstanding Voltage: 500V AC (60Sec Min)
 - Insulation Resistance: 1000MΩ Min
 - Contact Resistance: 100mΩ Max
 - RECOMMENDING A METAL MORE THAN 0.15mm THICK. PLEASE CONFIRM SOLDERABILITY, IF USE A METAL MASK LESS THAN 0.15mm THICK



: NO COPPER AREA
 : KEEP OUT AREA
 : PAD AREA

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE±0.05
KEEP ALL OFF THE COMPONENT PROJECT AREA



DONG GUAN MOARCONN ELECTRONIC Co.,Ltd.

X1	---	NEW RELEASE	Alexander	2020.07.04
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : MicroSIM Eject TrayH1.8	DRAWING: Alexander	DATE: 2020.07.04
DIMENSION TOLERANCE x. x : ± 0.20 x. xx : ± 0.10 x. xxx : ± 0.05 ANGULAR : ± 2°	PRODUCT NO. : MS180-T1151-01	CHECK:	DATE:
	DRAWING NO. : D-MS180-T1151-01	APPROVED:	DATE:
	SCALE: 1:1	DWG ID: C D	REV.: X1
		PAGE: 1 OF 1	